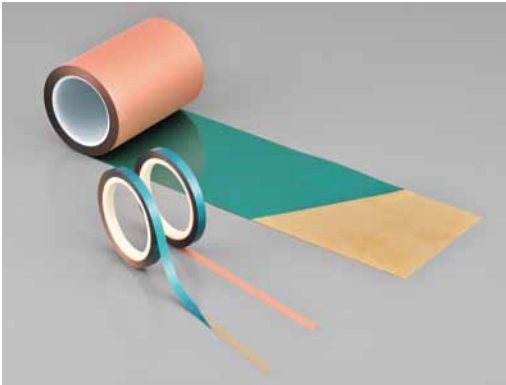
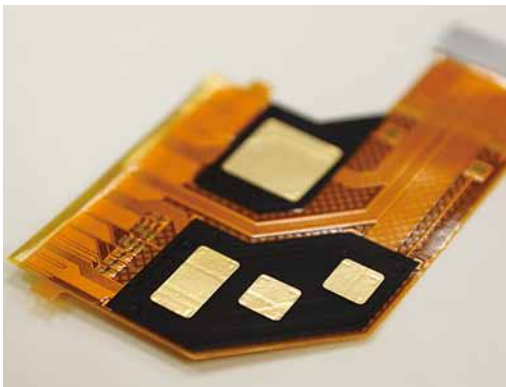


Free Grounding Film

FGF-500



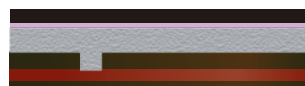
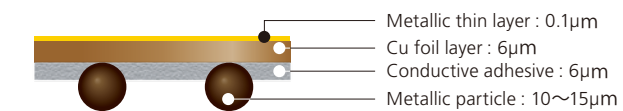
FGF-500 is a supplementary material to connect Ground joint on a top of TATSUTA EMI Shielding film.

FGF-500 can interconnect an outside ground such as a steal case or a metallic flame and FPC, and also support lead free solder.

Features

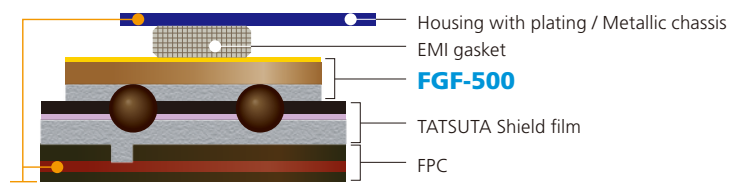
- ▶ **Strengthening GND joint on a partially multi layer**
With the existing measures it can make a synergetic effect as a new technology to reduce noise.
- ▶ **Can take Ground joint on a top of TATSUTA EMI Shielding film freely**
- ▶ **Keep stable Joint resistance by Au plating**
- ▶ **Total body of 12μm**
Enhanced the flexibility during an embedding process.

Cross Sectional Structure of FGF-500



FPC + Shield film

GND joint can be done from either a top or a bottom.



UL recognized component

UL94 V-0 (bonding Kapton 50H on one side)

*Kapton is Dupont's registered trademark

Environmental regulation

Environmental regulation	FGF-500
UL94 flame class	V-0
Halogen free	Applicable
RoHS Directives	Applicable
Lead free reflow-soldering	Applicable